



Material Content Data Sheet



Sales Product Name		ICE2QR4765Z		Issued		25. January 2018		
MA#		MA001860908						
Package		PG-DIP-7-3		Weight*		644.83 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.794	0.43	0.43	4333	4333
leadframe	inorganic material	phosphorus	7723-14-0	0.048	0.01		75	
	non noble metal	zinc	7440-66-6	0.194	0.03		300	
	non noble metal	iron	7439-89-6	3.872	0.60		6005	
wire	non noble metal	copper	7440-50-8	157.218	24.38	25.02	243811	250191
	noble metal	gold	7440-57-5	0.413	0.06	0.06	641	641
	encapsulation	organic material	carbon black	1333-86-4	2.353	0.36		3649
encapsulation	plastics	epoxy resin	-	63.534	9.85		98528	
	inorganic material	silicondioxide	60676-86-0	404.735	62.78	72.99	627657	729834
leadfinish	non noble metal	tin	7440-31-5	6.460	1.00	1.00	10017	10017
plating	noble metal	silver	7440-22-4	1.594	0.25	0.25	2472	2472
glue	plastics	epoxy resin	-	0.283	0.04		440	
	noble metal	silver	7440-22-4	1.336	0.21	0.25	2072	2512
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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